

10/092890
03/06/02

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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10092890	FILING DATE 03/06/2002	CLASS 25758	SUBCLASS 455	GAU 2588	EXAMINER V. YEVSIKOV
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**APPLICANTS: Lutz Markus;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		11403/13
Verified and Acknowledged Examiners's initials		
TITLE : SI wafer-cap/wafer bonding method using local laser energy, device produced by the method, and system used in the method		

U.S. DEPT. OF COMM. / PAT. & TM. PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
ISSUE FEE		Sheets Drwg.	Figs. Drwg.
Amount Due	Date Paid	Print Fig.	
Primary Examiner		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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